

THERMAL CHARACTERISTICS

Parameter	Symbol	Max	Unit
Junction-to-Case - Steady State (Note 1)	$R_{\theta JC}$	0.28	°C/W

ELECTRICAL CHARACTERISTICS (T_J = 25° C unless otherwise specified)

Parameter	Symbol	Test Condi	tion	Min	Тур	Мах	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 V, I_D =$	= 1 mA	1700	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = 1 mA, reference	ced to 25°C	-	0.46	-	V/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V,$	$T_J = 25^{\circ}C$	-	-	100	μΑ
		$v_{\rm DS} = 1700$ v	T _J = 175°C	-	-	1	mA
Gate-to-Source Leakage Current	I _{GSS}	V _{GS} = +25/-15 V,	V _{DS} = 0 V	-	-	±1	μΑ
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D =$	= 20 mA	1.8	2.75	4.3	V
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Gate Thicshold Voltage	VGS(TH)	$V_{GS} = V_{DS}, I_{D} = 20 IIIA$	1.0	2.75	4.5	v
Recommended Gate Voltage	V _{GOP}		-5	-	+20	V
Drain-to-Source On Resistance	R _{DS(on)}	V_{GS} = 20 V, I_D = 60 A, T_J = 25°C	-	28	40	mΩ
		$V_{GS} = 20 \text{ V}, \text{ I}_{D} = 60 \text{ A}, \text{ T}_{J} = 175^{\circ}\text{C}$	-	57	-	

TYPICAL CHARACTERISTICS

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TYPICAL CHARACTERISTICS

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Figure 16. Junction-to-Case Thermal Response

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		L1			
b2		A1			
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e1	b(4X)	C			
e ∠x ⊕ 0.254 (№) B A (M)				

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